

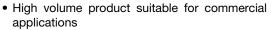
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Vishay

Lead (Pb)-free Thick Film, Rectangular Commodity Chip Resistors



FEATURES





• Excellent stability ($\Delta R/R \le 1$ % for 1000 h at 70 °C)

COMPLIANT

- · Lead (Pb)-free solder contacts on Ni barrier layer
- Metal glaze on ceramic
- Protective overglaze
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

STANDARD E	STANDARD ELECTRICAL SPECIFICATIONS										
MODEL	CASE SIZE INCH	CASE SIZE METRIC	POWER RATING P _{70 °C} W	LIMITING ELEMENT VOLTAGE MAX. V ≅	TEMPERATURE COEFFICIENT ppm/K	TOLERANCE %	RESISTANCE RANGE Ω	E-SERIES			
					± 100	± 1	1R0 to 10M	E24; E96			
CRCW0402C	0402	RR 1005M	0.063	50	± 200	Ξ Ι	1R0 to 9R76	L24, L90			
GNGVV0402G	0402	nn 1003W			± 200	± 5	1R0 to 10M	E24			
			Zero-Ohm-Resisto	or: $R_{\text{max.}} = 20$	mΩ, I _{max.} at 70 °C =	= 1.5 A					
					± 100	± 1	1R0 to 10M	E24; E96			
CRCW0603C	0603	RR 1608M	0.10	75	± 200	± 1	1R0 to 9R76	E24, E90			
ChCW0003C	0003	nn Iouoivi			± 200	± 5	1R0 to 10M	E24			
			Zero-Ohm-Resisto	or: R _{max.} = 20	mΩ, I _{max.} at 70 °C =	2.0 A					
					± 100	. 4	1R0 to 10M	F04. F06			
CDCM/000F C	0005	DD 0010M	0.125	150	± 200	± 1	1R0 to 9R76	E24; E96			
CRCW0805C	0805	RR 2012M			± 200	± 5	1R0 to 10M	E24			
			Zero-Ohm-Resisto	or: R _{max.} = 20	mΩ, I _{max.} at 70 °C =	2.5 A		•			
					± 100	. 4	1R0 to 10M	E04 E03			
CDCW1006 C	1006	RR 3216M	0.25	200	± 200	± 1	1R0 to 9R76	E24; E96			
CRCW1206C	1206	nn 3∠101VI			± 200	± 5	1R0 to 10M	E24			
			Zero-Ohm-Resisto	or: $R_{\text{max.}} = 20$	mΩ, I _{max.} at 70 °C =	= 3.5 A					

Notes

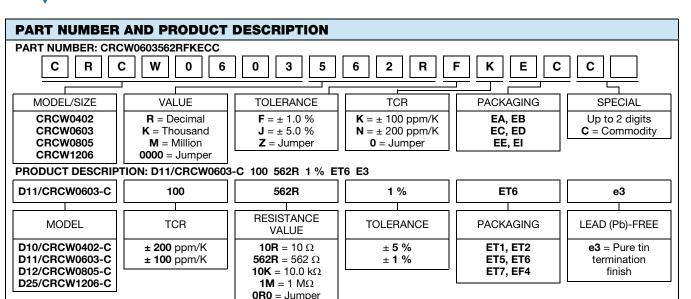
- These resistors do not feature a limited lifetime when operated within the permissible limits. However, resistance value drift increasing over
 operating time may result in exceeding a limit acceptable to the specific application, thereby establishing a functional lifetime.
- · Power rating depends on the max. temperature at the solder point, the component placement density and the substrate material.

TECHNICAL SPECIFICATIONS								
PARAMETER	UNIT	CRCW0402C	CRCW0603C	CRCW0805C	CRCW1206C			
Rated dissipation at 70°C (1)	W	0.063	0.10	0.125	0.25			
Limiting element voltage $U_{\text{max.}}$ AC/DC	V	50	75	150	200			
Insulation voltage U _{ins.} (1 min)	V	> 75	> 100	> 200	> 300			
Insulation resistance	Ω		> `	10 ⁹				
Category temperature range	°C		- 55 to	+ 155				
Failure rate h ⁻¹ 0.3 x 10 ⁻⁹								
Weight/1000 pieces	g	0.65	2	5.5	10			

Note

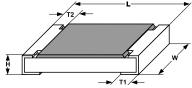
⁽¹⁾ The power dissipation on the resistor generates a temperature rise against the local ambient, depending on the heat flow support of the printed-circuit board (thermal resistance). The rated dissipation applies only if the permitted film temperature of 155 °C is not exceeded.

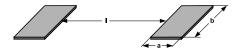




PACKAGING										
	REEL									
MODEL	TARE		PITCH	DIEGEO/	PACKAGING CODE					
WODEL	TAPE WIDTH	DIAMETER		PIECES/ REEL	PART NUMBER	PRODUCT DESC.				
	WIDIN			NEEL		PAPER				
		180 mm/7"		10 000	ED	ET7				
CRCW0402C	8 mm	254 mm/10"	2 mm	20 000	El	ET2				
		330 mm/13"		50 000		EF4				
	8 mm	180 mm/7"	4 mm	5000	EA	ET1				
CRCW0603C		254 mm/10"		10 000	EB	ET5				
		330 mm/13"		20 000	EC	ET6				
		180 mm/7"		5000	EA	ET1				
CRCW0805C	8 mm	254 mm/10"	4 mm	10 000	EB	ET5				
		330 mm/13"		20 000	EC	ET6				
		180 mm/7"		5000	EA	ET1				
CRCW1206C	8 mm	254 mm/10"	4 mm	10 000	EB	ET5				
		330 mm/13"		20 000	EC	ET6				

DIMENSIONS





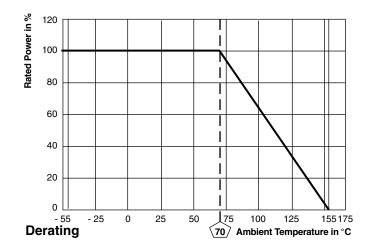
	SIZE DIMENSIONS (in millimeters)						SOLDER PAD DIMENSIONS (1) (in millimeters)					
	SIZE DIWIENSIONS (IN MINIMETERS)						REFLOW SOLDERING WAVE SOLDE				ERING	
INCH	METRIC	L	W	Н	T1	T2	а	b	ı	а	b	ı
0402	1005	1.0 ± 0.10	0.5 ± 0.05	0.30 ± 0.05	0.25 ± 0.10	0.2 ± 0.1	0.4	0.6	0.5			
0603	1608	1.60 ± 0.10	0.80 ± 0.10	0.45 ± 0.10	0.3 ± 0.2	0.3 ± 0.2	0.5	0.9	1.0	0.9	0.9	1.0
0805	2012	2.0 ± 0.10	1.25 ± 0.15	0.50 ± 0.10	0.35 ± 0.15	0.35 ± 0.2	0.7	1.3	1.2	0.9	1.3	1.3
1206	3216	3.05 ± 0.10	1.55 ± 0.10	0.55 + 0.10 - 0.05	0.35 ± 0.15	0.45 ± 0.2	0.9	1.7	2.0	1.1	1.7	2.3

Note

⁽¹⁾ The rated dissipation applies only if the permitted film temperature is not exceeded. Furthermore, a high level of ambient temperature or of power dissipation may raise the temperature of the solder joint, hence special solder alloys or boardmaterials maybe required to maintain the reliability of the assembly. Specified power rating above 125 °C requires dedicated heat-sink pads, which depend on boardmaterials. The given solder pad dimensions reflect the considerations for board design and assembly as outlined e.g. in standards IEC 61188-5-x, or in publication IPC-7351. They do not guarantee any supposed thermal properties, particularly as these are also strongly influenced by many other parameters. Still the given solder pad dimensions will be found adequate for most general applications.



FUNCTIONAL PERFORMANCE



TEST PROCEDURES AND REQUIREMENTS									
EN 60115-1	IEC 60068-2				REQUIREMENTS CHANC				
CLAUSE	TEST METHOD	TEST	PRO	OCEDURE	STABILITY CLASS 1 OR BETTER	STABILITY CLASS 2 OR BETTER			
			Stability for prod	luct types:					
				CRCWC e3	1 Ω to 10 MΩ	1 Ω to 10 MΩ			
4.5	-	Resistance		-	± 1 %	± 5 %			
4.8.4.2	-	Temperature coefficient		5/20) °C and 125/20) °C	± 100 ppm/K, ± 200 ppm/K	± 200 ppm/K			
4.13	-	Short time overload	$U = 2.5 \times \sqrt{P}$ duration:	$\frac{1}{70} \times R \le 2 \times U_{\text{max.}}$ Acc. to the style	$\pm (0.25 \% R + 0.05 \Omega)$	± (0.5 % R + 0.05 Ω)			
4.17.5	58 (Td)	Solderability	Pre-aging 4 h at 155 °C.	Solder bath method; Sn60Pb40 non activated flux; (235 ± 5) °C (2 ± 0.2) s	Good tinning (≥ 95 % covered) no visible damage				
4.17.3	38 (Tu)	Solderability	dryheat	Solder bath method; Sn96.5Ag3Cu0.5 non activated flux; (245 ± 5) °C (3 ± 0.3) s	Good tinning (≥ no visible	,			
4.18.2	58 (Td)	Resistance to soldering heat		bath method) °C; (10 ± 1) s	± (0.25 % R + 0.05 Ω)	± (0.5 % R + 0.05 Ω)			
4.19	14 (Na)	Rapid change of temperature	30 min. at - 55 °C; 30 min. at 125 °C; 5 cycles		± (0.25 % R + 0.05 Ω)	± (0.5 % R + 0.05 Ω)			
4.24	78 (Cab)	Damp heat, steady state	(40 ± 2) °C; 56 days; (93 ± 3) % RH		± (1 % R + 0.05 Ω)	± (2 % R + 0.1 Ω)			
4.23	-	Climatic sequence:		-					
4.23.2	2 (Ba)	Dry heat	125 °C; 16 h						
4.23.3	30 (Db)	Damp heat, cyclic	55 °C; ≥ 90 %	6 RH; 24 h; 1 cycle					
4.23.4	1 (Aa)	Cold	- 55 °C; 2 h 1 kPa; (25 ± 10) °C; 1 h 55 °C; ≥ 90 % RH; 24 h; 5 cycles		± (1 % R + 0.05 Ω)	± (2 % R + 0.1 Ω)			
4.23.5	13 (M)	Low air pressure							
4.23.6	30 (Db)	Damp heat, cyclic							
4.23.7	-	DC load	$U = \sqrt{P_7}$	$\frac{1}{10} \times R \leq U_{\text{max.}}$					



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TEST PROCEDURES AND REQUIREMENTS								
EN 60115 1	IEC 60068-2			REQUIREMENTS PERMISSIBLE CHANGE (ΔR)				
CLAUSE TEST METHOD		TEST	PROCEDURE	STABILITY CLASS 1 OR BETTER	STABILITY CLASS 2 OR BETTER			
			Stability for product types:					
			CRCWC e3	1 Ω to 10 $\text{M}\Omega$	1 Ω to 10 M Ω			
		Endurance	$U = \sqrt{P_{70} \times R} \le U_{\text{max.}};$ 1.5 h on; 0.5 h off;					
4.25.1	-	at 70 °C	70 °C; 1000 h	\pm (1 % R + 0.05 Ω)	± (2 % R + 0.1 Ω)			
			70 °C; 8000 h	\pm (2 % R + 0.1 Ω)	± (4 % R + 0.1 Ω)			
4.25.3	-	Endurance at 125 °C	125 °C, 1000 h	± (1 % R + 0.05 Ω)	± (2 % R + 0.1 Ω)			

APPLICABLE SPECIFICATIONS

• EN 60115-1 Generic specification • EN 140400 Sectional specification • EN 140401-802 Detail specification

• IEC 60068-2-X Variety of environmental test procedures

• IEC 60286-3 Packaging of SMD components

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